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**(54) METHOD FOR PROVIDING LATERAL THERMAL PROCESSING OF THIN FILMS ON LOW-TEMPERATURE SUBSTRATES**

VERFAHREN ZUR BEREITSTELLUNG EINER SEITLICHEN WÄRMEBEARBEITUNG VON DÜNN SCHICHTEN AUF NIEDRIGTEMPERATURSUBSTRATEN

PROCÉDÉ DE TRAITEMENT THERMIQUE LATÉRAL DE FILMS MINCES SUR DES SUBSTRATS À BASSE TEMPÉRATURE

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**Description****PRIORITY CLAIM**

**[0001]** The present application claims priority under 35 U.S.C. § 119(e)(1) to provisional application number 61/350,765 filed on June 2, 2010.

**BACKGROUND OF THE INVENTION****1. Technical Field**

**[0002]** The present invention relates to a method for curing thin films on substrates in general, and, in particular, to a method for thermally processing thin films on low-temperature substrates.

**2. Description of Related Art**

**[0003]** In general, thermal processing encompasses sintering, annealing, curing, drying, crystallization, polymerization, chemical reaction initiation and modulation, dopant drive-in, degasification, etc. Thermal processing of semiconductor thin films is typically performed in high temperature environments. For example, amorphous silicon (a-Si) is annealed at 1,100 °C, and silicon nanoparticle films are sintered at 900 °C. Thus, the high-temperature requirement for processing semiconductor thin films often mandates the usage of high-temperature substrates, such as fired ceramics or quartz, as the choice substrates for carrying semiconductor thin films. US-5,950,078 discloses a method for rapid thermally annealing a thin amorphous film.

**[0004]** Needless to say, it is more desirable to use low-temperature substrates, such as borosilicate or soda lime, as the choice substrates for carrying semiconductor thin films if possible because of their relatively low cost. Even more desirable substrate materials would be plastic (*i.e.*, polycarbonate, polyimide, PET, PEN, etc.) or paper because their cost is even lower.

**[0005]** However, the usage of equipment that can provide an equilibrium process, such as an oven, is not a viable option for thermally processing a semiconductor thin film on a low-temperature substrate. This is because the required temperature for annealing and sintering most, if not all, semiconductor thin films are considerably higher than the maximum working temperatures of low-temperature substrates such as polyimide and PET, which are around 450 °C and 150 °C, respectively.

**[0006]** The present disclosure provides a method for thermally processing thin films on low-temperature substrates.

**SUMMARY OF THE INVENTION**

**[0007]** In accordance with the present invention, there is provided a method for thermally processing a thin film as defined by claim 1.

**[0008]** All features and advantages of the present invention will become apparent in the following detailed written description.

**BRIEF DESCRIPTION OF THE DRAWINGS**

**[0009]** The invention itself, as well as a preferred mode of use, further objects, and advantages thereof, will best be understood by reference to the following detailed description of an illustrative embodiment when read in conjunction with the accompanying drawings, wherein:

Figures **1a-1b** depict a method for thermally processing a thin film;

Figures **2a-2b** depict a method for thermally processing a thin film, in accordance with an embodiment of the present invention;

Figures **3a-3b** depict a method for thermally processing a very thin film on a low-temperature substrate, in accordance with one embodiment of the present invention;

Figure **4** shows a thin film transistor (TFT) manufactured by the methods of the present invention;

Figure **5** shows a Raman spectrum of an e-beam coated amorphous silicon on a borosilicate glass before and after being exposed to pulsed radiation;

Figure **6** is a graph showing the selectivity of the pulsed radiation lateral thermal processing method; and

Figure **7** is a graph showing drain current versus drain-source voltage for the TFT from Figure **4**.

**DETAILED DESCRIPTION OF A PREFERRED EMBODIMENT**

**[0010]** When using a pulsed radiation thermal processing technique to thermally process a thin film on a substrate, the pulsed radiation emitted from flashlamps, directed plasma arcs (DPAs), lasers, microwaves, induction heaters or electron beams has the ability to preferentially heat the thin film over its substrate. In addition, because the heat capacity of the substrate is much larger than that of the thin film, and the time of heating is much shorter than the thermal equilibration time of the substrate, the substrate can serve as a heat sink to rapidly cool the thin film immediately after thermal processing.

**[0011]** Although pulsed radiation thermal processing allows a thin film to be heated to a much higher temperature than its substrate can normally withstand at thermal equilibrium, such thermal processing technique generally depends on the ability of a thin film to absorb the radiation that is used to heat the thin film. Thus, when a thin

film is very thin and/or somewhat transparent, it is quite difficult to thermally process the very thin film directly with the pulsed radiation thermal processing technique because the very thin film typically absorbs minimal radiation. Consequently, an improved method is required to thermally process a very thin film.

**[0012]** Referring now to the drawings, and in particular to Figures **1a-1b**, there are depicted a method for providing pulsed radiation thermal processing on a very thin film. Initially, a very thin film **12** is deposited on a substrate **14** via well-known vacuum techniques. Very thin film **12** may also be coated or printed on substrate **14**. Very thin film **12** can be a fully dense film or a particulate film. The thickness of very thin film **12** is preferably less than 10 microns. Next, an absorbing trace **11** is deposited on top of very thin film **12** to form a thin film stack **10**, as shown in Figure **1a**. Absorbing trace **11** is preferably made of a material that is more absorptive of pulsed radiation than very thin film **12**. Examples of absorbing trace **11** include metals or ceramics.

**[0013]** When thin film stack **10** is transiently irradiated (*i.e.*, via pulsed radiation) by a light source **15**, absorbing trace **11** is preferentially heated before very thin film **12**. Light source **15** can be a flashlamp, directed plasma arc (DPA), laser, microwave generator, induction heater or electron beam. As a result, the area (shaded area) within very thin film **12** and substrate **14** located underneath and adjacent to absorbing trace **11** is thermally processed by the heated absorbing trace **11**, as shown in Figure **1b**. The distance  $d_1$  within very thin film **12** that is thermally processed can be tens of microns.

**[0014]** With reference now to Figures **2a-2b**, there are illustrated a method for providing pulsed radiation thermal processing on a very thin film, in accordance with an embodiment of the present invention. Initially, a very thin film **23** is deposited on a substrate **24** via well-known vacuum techniques. Very thin film **23** can also be coated or printed on substrate **24**. Very thin film **23** can be a fully dense film or a particulate film. The thickness of very thin film **23** is preferably less than 10 microns. Next, absorbing traces **21, 22** are deposited on very thin film **23** to form a thin film stack **20**, as shown in Figure **2a**. Similar to absorbing trace **11** in Figure **1a**, absorbing traces **21, 22** are made of a material that is more absorptive of pulsed radiation than very thin film **23**. The absorbing traces **21, 22** are made of ceramics. The absorbing traces **21, 22** are formed on top of very thin film **23**.

**[0015]** Upon being exposed to pulsed radiation from a light source **25**, absorbing traces **21, 22** are preferentially heated over very thin film **23**. The heat from absorbing traces **21, 22** is then conducted to the area of very thin film **23** underneath and/or adjacent to absorbing traces **21, 22**, as shown in Figure **2b**. In Figure **2b**, an area  $d_2$  within very thin film **23** located between absorbing traces **21, 22** becomes thermally processed. The gap distance that can be thermally processed between absorbing traces **21** and **22** (*i.e.*, area  $d_2$ ) is generally larger than  $d_1$  from Figure **1b** since it is the overlap of the heat being

conducted by two absorbing traces **21, 22** and is preferably less than 100 microns. Furthermore, since the area within very thin film **23** located between absorbing traces **21** and **22** is thermally processed by the overlapping of heat being conducted from two absorbing traces **21, 22**, very thin film **23** tends to be more uniformly processed than the area of a thin film adjacent to only one absorbing trace (such as in Figure **1b**).

**[0016]** Substrate **14** in Figures **1a-1b** and substrate **24** in Figures **2a-2b** are preferably high-temperature substrates. However, thermal processing of very thin films can also be performed on low-temperature substrates (*i.e.*, maximum working temperatures of 150 °C or less) by applying heat spreading films before or after the application of the absorbing traces. Since the thermal conductivity of the heat spreading film is higher than that of the low temperature substrate, heat is preferentially conducted in the plane of the very thin film and the heat spreading film instead of the low temperature substrate after absorbing traces have been heated. The heat spreading film also acts as a thermal barrier layer to protect the low temperature substrate. In addition, the preferential conduction of heat in the plane of the very thin film increases the distance at which absorbing traces can be placed from each other. As a result, a lower energy light pulse can be used to process the very thin film, thus making the process more gentle on the low-temperature substrate. The heat spreading film is generally thicker than the very thin film and is generally transparent to the light used to heat the absorbing traces.

**[0017]** Referring now to Figures **3a-3b**, there are illustrated a method for thermally processing a very thin film on a low-temperature substrate, in accordance with one embodiment of the present invention. Initially, a heat spreading film **35** is deposited on a substrate **34** via well-known vacuum techniques. Heat spreading film **35** may be coated or printed on substrate **34**. A very thin film **33** is then deposited on top of heat spreading film **35** via well-known vacuum techniques. Very thin film **33** may be coated or printed on heat spreading film **35**. Very thin film **33** can be a fully dense film or a particulate film. The thickness of very thin film **33** is preferably less than 10 microns. Next, absorbing traces **31, 32** are deposited on very thin film **33** to form a thin film stack **30**, as shown in Figure **3a**. Similar to absorbing traces **21, 22** in Figure **2a**, absorbing traces **31, 32** are made of a material that is more absorptive of pulsed radiation than very thin film **33**. Examples of absorbing traces **31, 32** are made of ceramics. The absorbing traces **31, 32** are formed on top of very thin film **33**. Although heat spreading film **35** is shown to be formed underneath very thin film **33**, heat spreading film **35** can be formed on top of very thin film **33** or absorbing traces **31, 32**.

**[0018]** Upon being exposed to pulsed radiation from a light source **35**, absorbing traces **31, 32** are preferentially heated over very thin film **33** and heat spreading film **35**. The heat from absorbing traces **31, 32** is then conducted to the area of very thin film **33** and heat spreading film

**35** underneath and/or adjacent to absorbing traces **31**, **32**, as shown in Figure **3b**. In Figure **3b**, an area  $d_3$  within very thin film **33** and heat spreading film **35** located between absorbing traces **31**, **32** becomes thermally processed. The gap distance that can be thermally processed between absorbing traces **31** and **32** is preferably less than 100 microns.

**[0019]** There is a host of materials suitable for being heat spreading film **35**. For a low-temperature substrate such as PET, those materials may include high-temperature polymers (such as polyimide) or inorganic coatings such as sputtered metal oxides or spin on glass (SOG). For higher-temperature substrates such as polyimide, more suitable materials for heat spreading film **35** include inorganic coatings such as sputtered metal oxides or SOG. It is preferable that heat spreading film **35** be somewhat transparent in order to maintain transparency of the very thin film and still allow the selective heating to occur. The required thickness of heat spreading film **35** is a function of its thermal properties, the thickness and thermal properties of the underlying low temperature substrate, the desired processing temperature of very thin film **33**, the dimensions and spacing of absorbing traces **31**, **32**, and the input radiant heating profile.

**[0020]** One approach of applying a heat spreading film to a high-temperature substrate is to first apply a polymeric coating, which has lower thermal conductivity than the high-temperature substrate, to the high-temperature substrate followed by the application of a heat spreading film. This practice retards the diffusion of heat into the thermally conductive substrate and allows a very thin film to be processed. An alternative to the polymeric coating is to use a high-temperature, low-thermal conductivity inorganic film so that it can withstand a higher temperature during thermal processing.

**[0021]** One method to achieve a high-temperature, low-thermal conductivity inorganic film is to make the inorganic film porous by using a SOG and load it with porous particles. For example, such an inorganic film can be made by using silica aerogel nanoparticles loaded in a SOG. The resulting inorganic film appears to have a thermal conductivity of the order of (or even lower than that of) PET (*i.e.*, 0.24 W/m<sup>2</sup>·K). Since the aerogel particles have the SOG matrix, the inorganic film is much more durable than a typical aerogel film.

**[0022]** The thermal processing of the very thin film can be tuned by varying the power and length of the pulsed radiation. Multiple pulses can be used as well as adjusting the pulse repetition frequency. The shape of the pulse can be changed using pulse width modulation to further adjust the heating profile. When the pulse length is shorter than the thermal equilibration time of the low-temperature substrate, that is, perpendicular to the plane of the low-temperature substrate, a stronger thermal gradient and higher peak temperature can be generated in it, thereby preferentially heating the very thin film adjacent to the absorbing traces. The temperature in the very thin film is more intensely processed near the absorbing trac-

es relative to regions farther away from the absorbing traces. Furthermore, pulsed radiation allows the peak processing temperature to be greater than the maximum equilibrium working temperature of a substrate. For example, 150 micron thick PET thermally equilibrates across its thickness in about 35 ms. Thus, a stronger thermal processing gradient as well as a higher peak temperature can be produced without damaging the low-temperature substrate with a 300  $\mu$ s pulse than with a 10 ms pulse. A 100 ms pulse can still heat the very thin film located between the absorbing traces, but the peak temperature that can be maintained is very close to its maximum equilibrium working temperature of 150 °C. In sum, the maximum peak temperature that can be achieved in the very thin film without damaging the low-temperature substrate of a longer pulse is less than that of a short pulse, but the lateral processing length is correspondingly longer also. Since the thermal processing of the very thin film is usually Arrhenius in nature, *i.e.*, the thermal processing is generally related to the exponential of the processing temperature times time, a shorter pulse can process the very thin film more effectively than a longer pulse without damaging the low-temperature substrate.

**[0023]** The thickness, width, and spacing of absorbing traces as well as the thickness and thermal properties of a very thin film and underlying layers also contribute to the heating profile seen by the very thin film upon being exposed by pulsed radiation.

**[0024]** The method of the present invention can process very thin films that are not particularly radiation absorbing. This is particularly relevant to the fabrication of thin film transistors (TFTs) that are very desirable because of their low cost and high performance.

**[0025]** Referring now to Figure **4**, there is depicted a TFT **40** manufactured by the above-mentioned pulsed radiation thermal processing technique. As shown, a thin dielectric layer **44** is placed on top of two absorbing traces **41** and **42** that are located adjacent to a very thin film **43**. A conductive trace **45** is located on top of dielectric layer **44** and absorbing traces **41** and **42**. Absorbing traces **41**, **42** are electrically conductive and form the source and the drain of a TFT, respectively. Conductive trace **45** forms the gate of the TFT. The area located between absorbing traces **41** and **42** within very thin film **43** that has been thermally processed is a semiconductor forms the active channel of the TFT. As shown in Figure **4**, the cured area (shaded area) includes the gate oxide and the gate. However, both the gate oxide and the gate are applied after the curing of the very thin film **43**.

**[0026]** Very thin film **43** is cured primarily between absorbing traces **41** and **42**. Thus, sources and drains can be patterned (or printed) on a very large area, and very thin film **43** can even be coated over an entire substrate **46**. Since a cured semiconductor generally has a higher conductivity than an uncured one, the fact that the semiconductor becomes cured primarily in the channel of the TFT, the parasitic capacitance of the semiconductor is

reduced. The reduced need for registration and critical dimensions means that the above-mentioned TFT can be completely printed *en mass*.

**[0027]** An example of a method for making a TFT, such as TFT 40, is described as follows. When making a TFT, microcrystalline silicon ( $\mu\text{X-Si}$ ) is more desirable as a semiconductor than amorphous silicon (a-Si) because  $\mu\text{X-Si}$  has higher mobility and therefore enables a faster switching TFT. It is usually easier to deposit a-Si followed by a thermal anneal to convert a-Si to  $\mu\text{X-Si}$  than to deposit  $\mu\text{X-Si}$  directly. For example, a 200 nm film of a-Si on a 500  $\mu\text{m}$  borosilicate wafer can be converted to  $\mu\text{X-Si}$  (with an N<sub>2</sub> purge) by using a light pulse from a PulseForge® 3300 system (manufactured by NovaCentrix in Austin, Texas) at a threshold voltage of 650 V and a pulse length of 100  $\mu\text{s}$ . The light pulse has an intensity of about 35 kW/cm<sup>2</sup>, which corresponds to a radiant exposure of about 3.5 J/cm<sup>2</sup>.

**[0028]** With reference now to Figure 5, there is illustrated a Raman spectrum of 200 nm a-Si film that was e-beam sputtered coated on a borosilicate glass before and after being exposed to the above-mentioned light pulse. The a-Si film is annealed by the light pulse and is converted to  $\mu\text{X-Si}$ . The light pulse is needed to overcome the fact that a 200 nm a-Si coating only absorbs a portion of the emitted light.

**[0029]** An identical borosilicate wafer is patterned with gold contact source/drain lines to form an eventual TFT of various widths (5-50  $\mu\text{m}$ ) and separations (5-50  $\mu\text{m}$ ). All traces are 5 mm long. The gold patterning is followed by an identical broadcast electron beam sputtered deposition of 200 nm of a-Si described above over the borosilicate wafer. The borosilicate wafer is then processed via the above-mentioned PulseForge® 3300 system at a much lower voltage (*i.e.*, 550 V for 250  $\mu\text{s}$ ). The radiant power was 24 kW/cm<sup>2</sup>, and the radiant exposure was 5.9 J/cm<sup>2</sup>. Note that this level of power is below the threshold intensity described above for converting a-Si to  $\mu\text{X-Si}$ . Since gold is very absorbing of the light pulse, more energy is absorbed at those locations.

**[0030]** Referring now to Figure 6, there is illustrated the selectivity of the pulsed radiation thermal processing method. The graph shows a comparison of the Raman spectrum of the thin silicon film between two different gold line pair widths (50  $\mu\text{m}$  and 20  $\mu\text{m}$ ) and identical spacing (50  $\mu\text{m}$ ) between the gold traces. The graph shows that the space between the 50  $\mu\text{m}$  traces has been converted to  $\mu\text{X-Si}$ , whereas the space between the 20  $\mu\text{m}$  wide traces is unconverted. Similarly, the silicon film on the rest of the wafer is unconverted. This technique has converted the a-Si to  $\mu\text{X-Si}$  only between the gold patterned traces and nowhere else achieving automatic registration.

**[0031]** After selective conversion of a-Si to  $\mu\text{X-Si}$  between the absorbing traces has been achieved, a TFT device can be fabricated using a spin-on barium-strontium-titanate (BST) ceramic as the dielectric layer. This dielectric material has a relatively high dielectric constant

k (~300), which allows a high electric field to be imparted to the field-effect channel of the TFT at low gate voltage. A silver gate metal is vacuum deposited onto the BST gate dielectric layer to complete the TFT.

**[0032]** Electrical testings can be performed on the TFT to determine if the drain current can be enhanced by applying a positive gate voltage. Since  $\mu\text{X-Si}$  is slightly n-type, a positive gate voltage should enhance the electron concentration in the channel and result in an increased drain current ( $I_d$ ).

**[0033]** With reference now to Figure 7, there is illustrated a graph showing drain current ( $I_d$ ) versus drain-source voltage ( $V_{ds}$ ) for TFT 40 from Figure 4. Note that at positive gate voltage ( $V_g$ ), the drain current ( $I_d$ ) is enhanced and has the saturation shape one expects for a field-effect TFT. The linear I-V characteristic observed at negative gate voltage indicates TFT 40 is behaving as a regular resistor when the negative gate voltage is applied. Reasons for this are unknown at this time but may be due to hole injection from the source and drain contacts. This effect, if present, is normally reduced/eliminated by suitably doping the contact regions in order to "block" hole injection.

**[0034]** In summary, using pulsed light annealing of an a-Si thin film with laterally positioned metal source-drain contacts can be "sub-threshold" annealed to a microcrystalline state within the region between the source-drain contacts. This has great benefit for the microelectronics industry since micro (and nano)-crystalline silicon films have high carrier mobility and other desirable features that enhance the performance of thin film devices. Furthermore, since one can convert only the a-Si in the region between source/drain contacts, leaving the surrounding regions of the a-Si to remain in a high-resistance amorphous state, and thus not require patterning or otherwise isolation to limit such deleterious effects as parasitic capacitances which limit device speed and increase power dissipation.

**[0035]** As has been described, the present invention provides a method for thermally processing thin films on low-temperature substrates. The method of the present invention according to the claims also enables a TFT to be manufactured in a top gate configuration (*i.e.*, gate on top) with minimal registration. Two absorbing traces form a source and drain of a TFT. Before the application of the gate oxide and the gate, the thin film material is preferentially thermally processed between the two absorbing ceramic traces. The method of the present invention has the effect of selectively curing the thin film material without the need to precisely deposit the material in the channel of the TFT.

**[0036]** While the invention has been particularly shown and described with reference to a preferred embodiment, it will be understood by those skilled in the art that various changes in form and detail may be made therein without departing from the scope of the invention.

**Claims**

1. A method for thermally processing a thin film, said method comprising:

patterning two light-absorbing traces on top of a thin film, wherein said two absorbing traces are made of ceramic which is more absorptive of pulsed radiation than said thin film, wherein said thin film is located on top of a substrate; irradiating said two absorbing traces with at least one electromagnetic pulse from a light source to heat up said two absorbing traces; and allowing heat from said two absorbing traces to thermally process said thin film.

2. The method of Claim 1, wherein said substrate has a maximum working temperature of less than 450°C.

3. The method of Claim 1, wherein said method further includes providing a heat spreading layer between said thin film and said substrate, wherein the thermal conductivity of the heat spreading layer is higher than that of the substrate.

4. The method of Claim 1, wherein said electromagnetic pulse is provided from a flashlamp.

5. The method of Claim 1, wherein said electromagnetic pulse is provided from a directed plasma arc.

6. The method of claim 1 wherein the two absorbing traces are spaced apart.

7. The method of claim 1 wherein the distance between two absorbing traces is less than 100 microns.

**Patentansprüche**

1. Verfahren zur thermischen Verarbeitung eines Dünnsfilms, wobei das Verfahren Folgendes umfasst:

Strukturieren von zwei lichtabsorbierenden Spuren auf der Oberseite eines Dünnsfilms, wobei die beiden absorbierenden Spuren aus Keramik bestehen, die Impulsstrahlung besser absorbiert als der Dünnsfilm, wobei sich der Dünnsfilm auf der Oberseite eines Substrats befindet; Bestrahlen der beiden absorbierenden Spuren mit zumindest einem elektromagnetischen Impuls von einer Lichtquelle, um die beiden absorbierenden Spuren zu erhitzen; und Zulassen, dass Wärme von den beiden absorbierenden Spuren den Dünnsfilm thermisch verarbeiten.

2. Verfahren nach Anspruch 1, wobei das Substrat eine

maximale Arbeitstemperatur von weniger als 450 °C aufweist.

3. Verfahren nach Anspruch 1, wobei das Verfahren außerdem das Bereitstellen einer Wärmeverteilungsschicht zwischen dem Dünnsfilm und dem Substrat umfasst, wobei die Wärmeleitfähigkeit der Wärmeverteilungsschicht höher ist als die des Substrats.

4. Verfahren nach Anspruch 1, wobei der elektromagnetische Impuls von einer Blitzlampe bereitgestellt wird.

5. Verfahren nach Anspruch 1, wobei der elektromagnetische Impuls von einem gerichteten Plasmalichtbogen bereitgestellt wird.

6. Verfahren nach Anspruch 1, wobei die zwei absorbierenden Spuren voneinander beabstandet sind.

7. Verfahren nach Anspruch 1, wobei der Abstand zwischen den beiden absorbierenden Spuren weniger als 100 µm beträgt.

**Revendications**

1. Procédé de traitement thermique d'un film mince, ledit procédé comprenant les étapes consistant à :

former deux traces absorbant la lumière sur une partie supérieure d'un film mince, les deux traces absorbantes étant constituées de céramique qui absorbe plus un rayonnement pulsé que ledit film mince, dans lequel ledit film mince est situé sur une partie supérieure d'un substrat ; irradier lesdites deux traces absorbantes à l'aide d'au moins une impulsion électromagnétique d'une source lumineuse pour chauffer lesdites deux traces absorbantes ; et permettre à la chaleur provenant desdites deux traces absorbantes de traiter thermiquement ledit film mince.

2. Procédé selon la revendication 1, dans lequel ledit substrat a une température de travail maximale inférieure à 450 °C.

3. Procédé selon la revendication 1, dans lequel ledit procédé comprend en outre la fourniture d'une couche d'étalement de chaleur entre ledit film mince et ledit substrat, dans lequel la conductivité thermique de la couche d'étalement de chaleur est supérieure à celle du substrat.

4. Procédé selon la revendication 1, dans lequel ladite impulsion électromagnétique est fournie par une lampe éclair.

5. Procédé selon la revendication 1, dans lequel ladite impulsion électromagnétique est fournie par un arc plasma dirigé.
6. Procédé selon la revendication 1, dans lequel les deux traces absorbantes sont espacées l'une de l'autre. 5
7. Procédé selon la revendication 1, dans lequel la distance entre deux traces absorbantes est inférieure à 100 microns. 10

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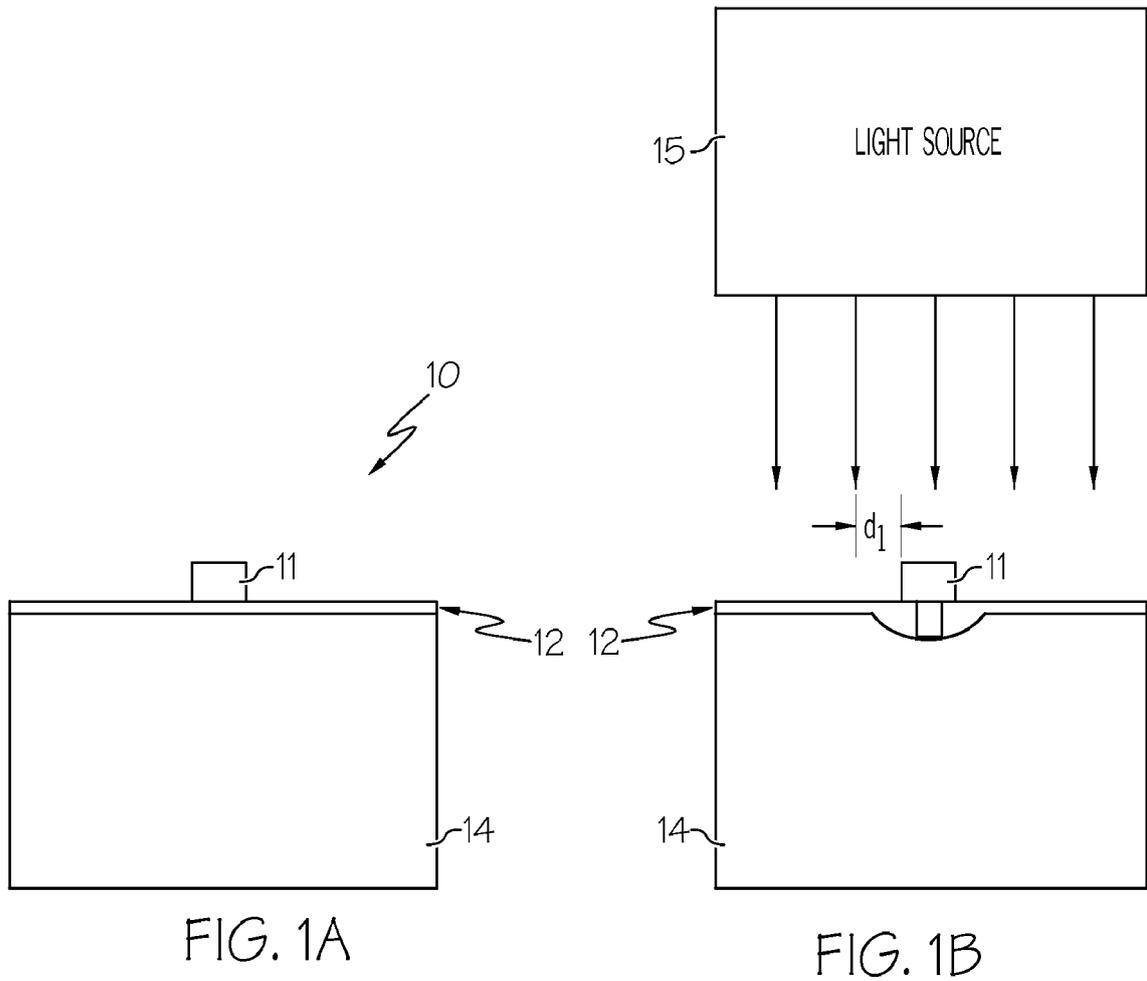
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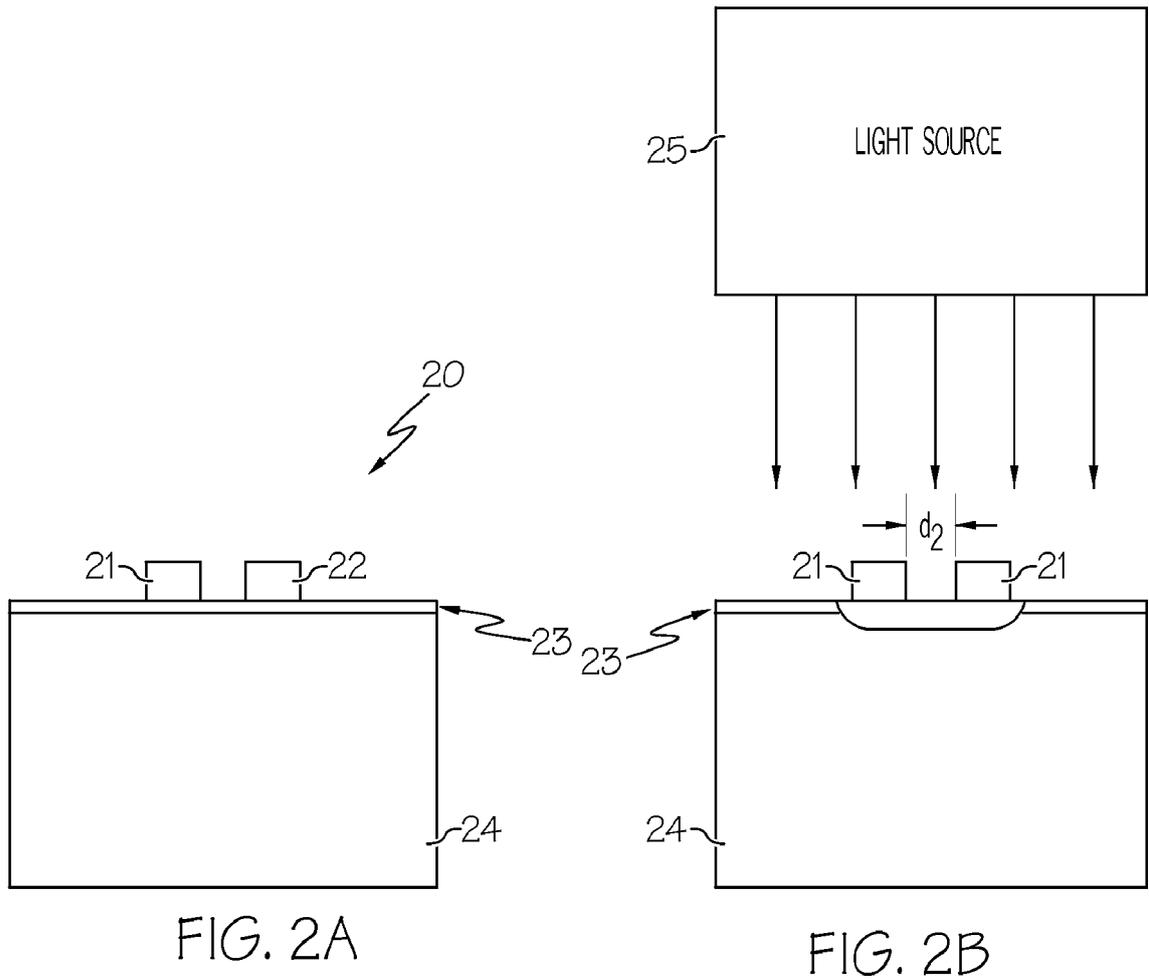


FIG. 2A

FIG. 2B

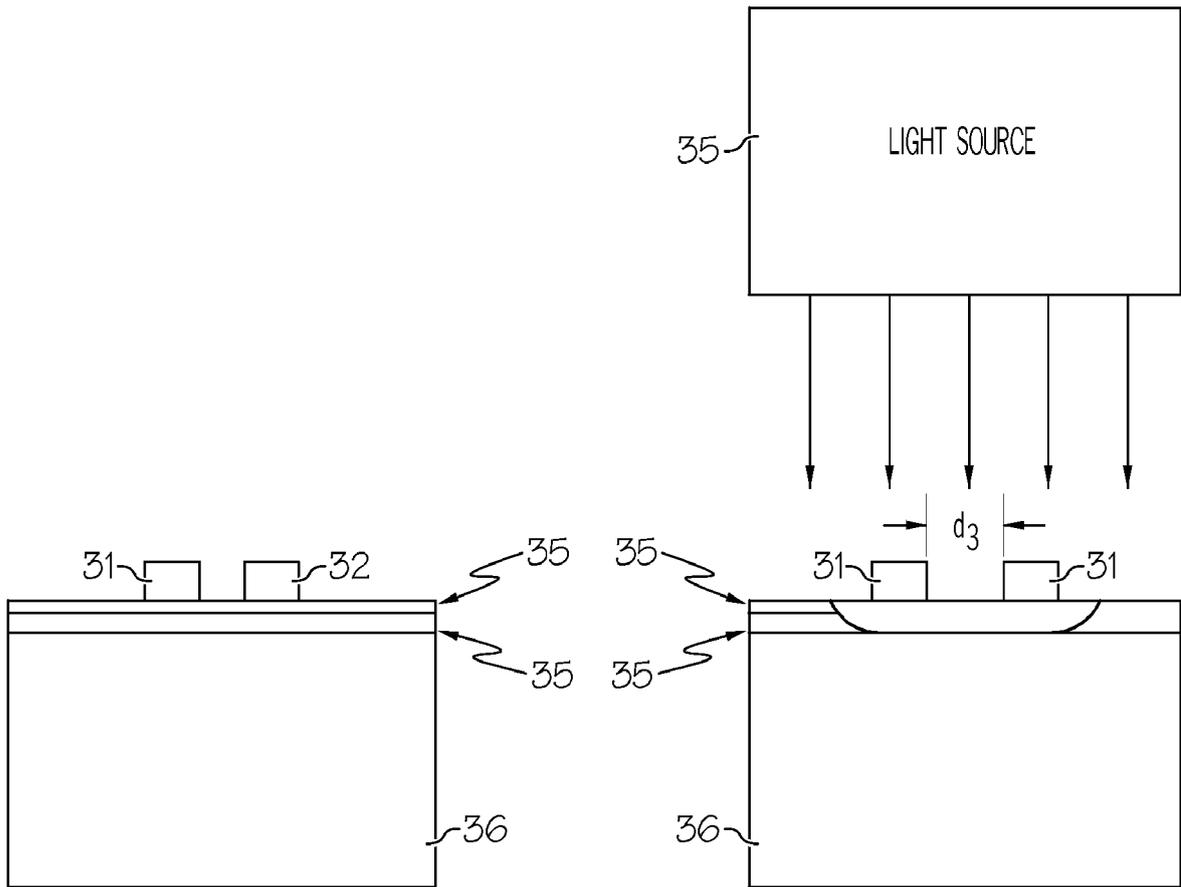


FIG. 3A

FIG. 3B

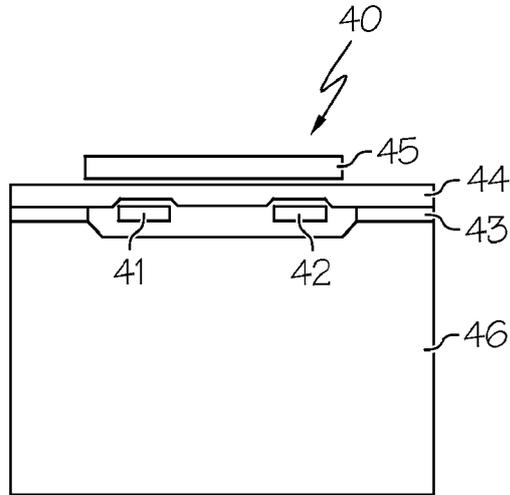


FIG. 4

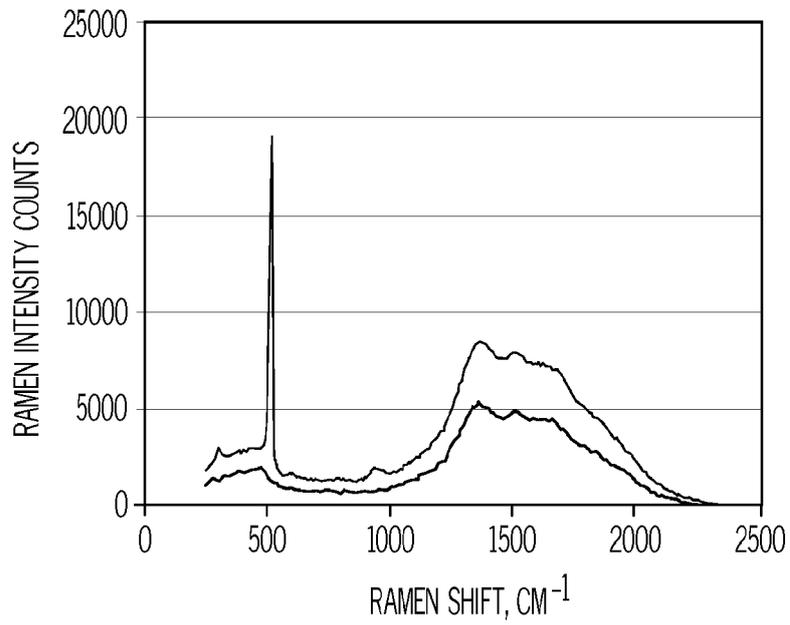


FIG. 5

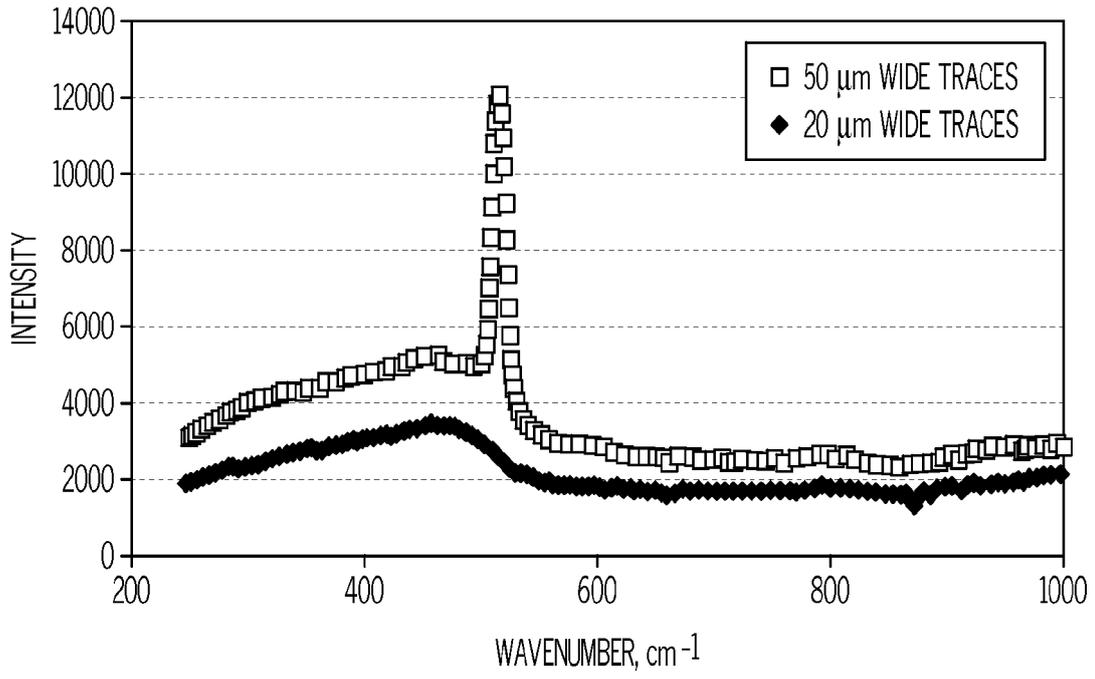


FIG. 6

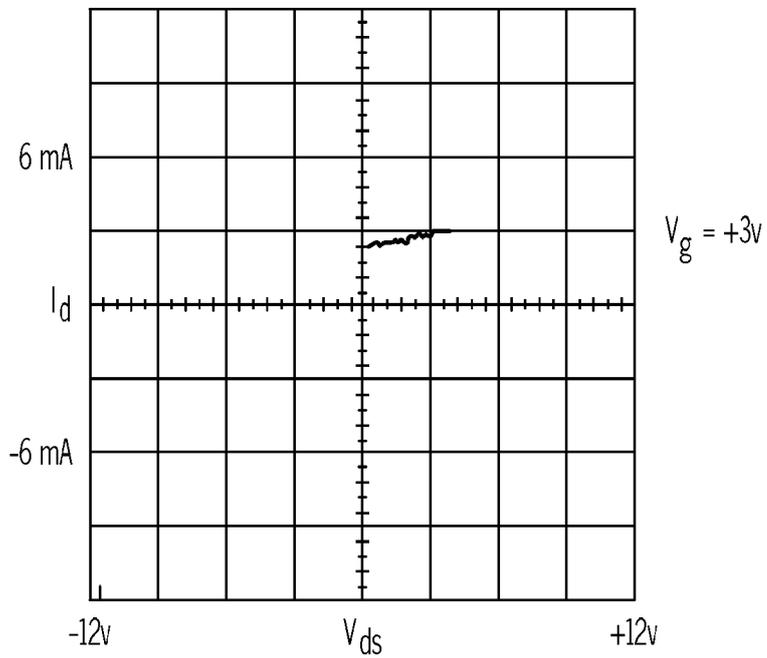


FIG. 7

**REFERENCES CITED IN THE DESCRIPTION**

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**Patent documents cited in the description**

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